BW Papersystems

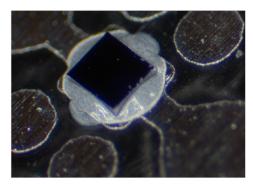
BW Bielomatik



TagLiner

EN







High Volume RFID Inlay Manufacturing Machine Features

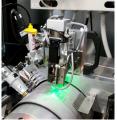
- Unrivalled gross output of up to 48.000 uph
- High throughput even at longer product pitches
- Simple single-track design for easy operation
- Shortest collet change times
- Very short setup times due to simple curing system
- High speed servo-controlled thermo compression curing system - better control of impact, force and height

- · High precision glue dispense system
- Works with both transparent and non-transparent substrates
- Full high-resolution vision inspections on glue, die, attach and cure without compromising on uph
- Major chip brands (NXP, Impinj, ...) fully qualified on environmental and mechanical reliability



TagLiner



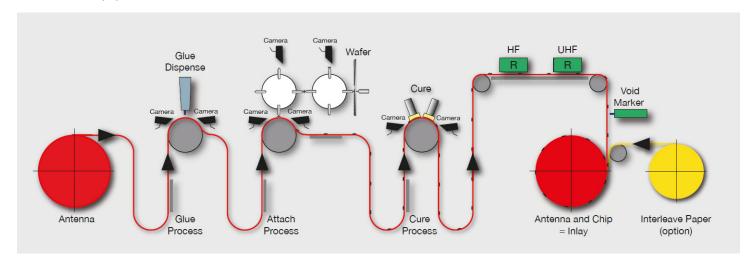




High Volume RFID Inlay Manufacturing Machine

The TagLiner is the highest capacity chip attach solution in the RFID industry. Applying best practices from the semiconductor industry, it greatly overcomes existing process bottlenecks. Each process station is using the same modular ultrafast index station, allowing for extremely precise positioning. Very high bonding quality can be achieved, demonstrated with a durability which proves to be best in class under mechanical stress testing. The TagLiner also targets the use of simpler and cheaper raw materials such as non-transparent substrates, like paper.

Technical details		
Processing width	max.	6.5" / 165 mm
Unhampered machine speed	max.	48000 uph (gross speed)
Glue dispense system		Volumetric
Smallest chip	min.	0.2 mm
High speed thermo compression curing system		Servo-driven, one or two units
Wafer mapping		All common formats supported
Wafer table		12"/8" automatic



Introduction of ITEC



ITEC was formed in 1991 as a division of Philips (subsequently NXP and Nexperia) to provide semiconductor manufacturing equipment and automation solutions.

In 2021, ITEC became an independent company within the Nexperia group of companies. ITEC provides the highest productivity assembly, test, inspection and smart manufacturing platforms, targeting mass volume manufacturing from semiconductor to RFID and LED devices.

ITEC is headquartered with a R&D team in Nijmegen, Netherlands, and has a large supply chain and customer support office in Hongkong.

BW Papersystems / ITEC Partnership Model

Providing the BEST out of TWO TEAMS

Building your success based on joint expertise, know-how and professional services:

- Best-in-class RFID conversion solutions
- Best-in-class die attach quality & productivity technology
- \bullet Top-level expertise in process integration ϑ manufacturing excellence

Seamlessly integrated by ITEC:

- One contact for commercial discussions
- One contact for delivery: transparent and reliable
- One contact for support: direct access to the service team

12/2022

